

Attorney Docket No: SEM4492P1120US
Corporate Docket No: P99-0023US

ABSTRACT OF THE DISCLOSURE

In an electroplating reactor for plating a spinning wafer, a diffusion plate is supported above an anode located within a cup filled with process fluid within the reactor.

The diffusion plate includes a plurality of openings which are arranged in a spiral pattern.

5 The openings allow for an improved plating thickness distribution on the wafer surface.

The openings can be elongated slots curved along the direction of the spiral path.

0988200-0544
T.D.T. 90" 60228850